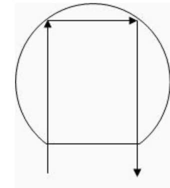
Part Number	Customer

Category		**Parameter**	**Specification**	**Measurement Method**
OverallWafer	1.0	Diameter	100.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	{110} +/- 0.5 degree	Customer supplied material
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Customer supplied material
	4.0	Secondary Flat Orientation	none	Customer supplied material
	5.0	Overall Thickness	300.00 +/- 11.00 µm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process
	7.0	Bow	<60.00µm	Estimate ADE to ASTM F534, 100%
	8.0	Warp	<60.00µm	Estimate ADE to ASTM F534, 100%
	9.0	Edge Chips	0	Bright Light, 100%
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Customer supplied material
	12.0	Handle Orientation	{100} +/- 0.5 degree	Customer supplied material
	13.0	Handle Thickness	250.00 +/- 10.00 µm	ADE, 100%
	14.0	Handle Doping Type	P	Customer supplied material
	15.0	Handle Dopant	Boron	Customer supplied material
	16.0	Handle Resistivity	>15 Ohm-cm	Customer supplied material
	17.0	Backside Finish	Polished with lasermark	Guaranteed by process
DeviceSilicon	21.0	Device Growth Method	CZ	Customer supplied material
	22.0	Device Orientation	{100} +/- 0.5 degree	Customer supplied material
	23.0	Nominal Thickness	50.00 +/- 1.00 µm	Single point ADE, 100% (note3)
	24.0	Distance to device silicon edge from wafer edge	< 2mm	Typical by Process
	25.0	Device Doping Type	P	Customer supplied material
	26.0	Device Dopant	Boron	Customer supplied material
	27.0	Device Resistivity	<0.0015 Ohmcm	Customer supplied material
	28.0	Surface Voids	None	Bright Light, 100% (note2)
	29.0	Haze	None	Bright Light, 100% (note2)
	30.0	Scratches	none on the front-side	Bright Light, 100% (note2)

Part Number	Customer		
Category	**Parameter**	**Specification**	**Measurement Method**
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	

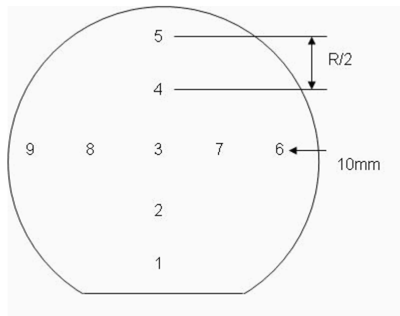
Explanatory Notes

1. Microscope inspection performed using microscope scan as below. 5x objective.



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information